



Material Content Data Sheet



Sales Product Name				BSZ120P03NS3E G		Issued		22. January 2018	
MA#				MA001407778					
Package				PG-TSDSON-8-2		Weight*		39.87 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.346	3.38	3.38	33750	33750	
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		53		
	non noble metal	zinc	7440-66-6	0.008	0.02		210		
	non noble metal	iron	7439-89-6	0.168	0.42		4205		
wire	non noble metal	copper	7440-50-8	6.808	17.08	17.53	170750	175218	
	non noble metal	copper	7440-50-8	0.050	0.13	0.13	1261	1261	
	encapsulation	organic material	carbon black	1333-86-4	0.038	0.09		941	
	plastics	epoxy resin	-	1.932	4.85		48464		
	inorganic material	silicondioxide	60676-86-0	16.790	42.11	47.05	421118	470523	
leadfinish	non noble metal	tin	7440-31-5	0.392	0.98	0.98	9832	9832	
plating	noble metal	silver	7440-22-4	0.963	2.41	2.41	24143	24143	
solder	noble metal	silver	7440-22-4	0.037	0.09		936		
	non noble metal	tin	7440-31-5	0.030	0.07		749		
	non noble metal	lead	7439-92-1	1.426	3.58	3.74	35771	37456	
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		27		
	non noble metal	zinc	7440-66-6	0.004	0.01		108		
	non noble metal	iron	7439-89-6	0.086	0.22		2163		
heat sink CLIP	non noble metal	copper	7440-50-8	3.501	8.78	9.01	87816	90114	
	inorganic material	phosphorus	7723-14-0	0.002	0.00		47		
	non noble metal	zinc	7440-66-6	0.008	0.02		189		
	non noble metal	iron	7439-89-6	0.151	0.38		3785		
	non noble metal	copper	7440-50-8	6.127	15.37	15.77	153682	157703	
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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